

# PATENT ASSIGNMENT

Electronic Version v1.1  
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
<b>CONVEYING PARTY DATA</b>											
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Masanobu KUSUNOKI</td> <td>12/09/2006</td> </tr> <tr> <td>Keitaro HARADA</td> <td>11/09/2006</td> </tr> <tr> <td>Masayoshi YOKOO</td> <td>11/09/2006</td> </tr> <tr> <td>Yoshinobu TAKANO</td> <td>07/09/2006</td> </tr> </tbody> </table>		Name	Execution Date	Masanobu KUSUNOKI	12/09/2006	Keitaro HARADA	11/09/2006	Masayoshi YOKOO	11/09/2006	Yoshinobu TAKANO	07/09/2006
Name	Execution Date										
Masanobu KUSUNOKI	12/09/2006										
Keitaro HARADA	11/09/2006										
Masayoshi YOKOO	11/09/2006										
Yoshinobu TAKANO	07/09/2006										
<b>RECEIVING PARTY DATA</b>											
<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 20%;">Name:</td> <td>Tohoku Seiki Industries, Ltd.</td> </tr> <tr> <td>Street Address:</td> <td>1246, Tachiyagawa 3-chome, Yamagata-shi</td> </tr> <tr> <td>City:</td> <td>Yamagata</td> </tr> <tr> <td>State/Country:</td> <td>JAPAN</td> </tr> <tr> <td>Postal Code:</td> <td>990-2251</td> </tr> </table>		Name:	Tohoku Seiki Industries, Ltd.	Street Address:	1246, Tachiyagawa 3-chome, Yamagata-shi	City:	Yamagata	State/Country:	JAPAN	Postal Code:	990-2251
Name:	Tohoku Seiki Industries, Ltd.										
Street Address:	1246, Tachiyagawa 3-chome, Yamagata-shi										
City:	Yamagata										
State/Country:	JAPAN										
Postal Code:	990-2251										
<b>PROPERTY NUMBERS Total: 1</b>											
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 30%;">Property Type</th> <th style="width: 70%;">Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>10594153</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	10594153						
Property Type	Number										
Application Number:	10594153										
<b>CORRESPONDENCE DATA</b>											
<p>Fax Number: (703)684-1157</p> <p><i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 7036841120</p> <p>Email: sbrown@mmiplaw.com</p> <p>Correspondent Name: John R. Mattingly, Mattingly &amp; Malur</p> <p>Address Line 1: 1800 Diagonal Rd.</p> <p>Address Line 2: Suite 370</p> <p>Address Line 4: Alexandria, VIRGINIA 22314</p>											
ATTORNEY DOCKET NUMBER:	SAK-5524										
NAME OF SUBMITTER:	John R. Mattingly										
Total Attachments: 1											

CH \$40.00 10594153

**501210234**

**PATENT**  
**REEL: 024566 FRAME: 0018**



# ASSIGNMENT

( 譲 渡 証 )

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by TOHOKU SEIKI INDUSTRIES, LTD.  
a corporation organized under the laws of Japan,  
located at 1246, Tachiyagawa 3-chome, Yamagata-shi, Yamagata 990-2251 Japan  
receipt of which is hereby acknowledged I do hereby sell and assign to said TOHOKU SEIKI INDUSTRIES, LTD.,  
its successors and assigns, all my right, title and interest, in and for the United States of America,  
in and to

## PROCESS FOR FORMING THINFILM AND SYSTEM FOR FORMING THIN FILM

invented by me (if only one is named below ) or us (if plural inventors are named below ) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be grant

to be held and enjoyed by said TOHOKU SEIKI INDUSTRIES, LTD.  
its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substit

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said TOHOKU SEIKI INDUSTRIES, LTD.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u>M. Kusumoto</u>	<u>12/09/06</u>
2) <u>Hirotaka Horada</u>	<u>11/09/06</u>
3) <u>Managoshi Yaboo</u>	<u>11/09/2006</u>
4) <u>Yoshinobu Takano</u>	<u>07/09/2006</u>
5) _____	_____
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____